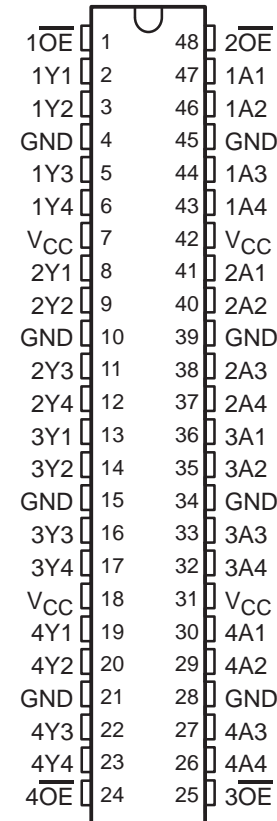


SN54ALVTH162244, SN74ALVTH162244 2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCES074E – JUNE 1996 - REVISED JANUARY 1999

- State-of-the-Art Advanced BiCMOS Technology (ABT) *Widebus*™ Design for 2.5-V and 3.3-V Operation and Low Static Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Power Off Disables Outputs, Permitting Live Insertion
- High-Impedance State During Power Up and Power Down Prevents Driver Conflict
- Uses Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Output Ports Have Equivalent 30- Ω Series Resistors, So No External Resistors Are Required
- Auto3-State Eliminates Bus Current Loading When Output Exceeds $V_{CC} + 0.5$ V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model; and Exceeds 1000 V Using Charged-Device Model, Robotic Method
- Flow-Through Architecture Facilitates Printed Circuit Board Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

SN54ALVTH162244 . . . WD PACKAGE
SN74ALVTH162244 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



NOTE: For order entry:
The DGG package is abbreviated to G, and
the DGV package is abbreviated to V.

description

The 'ALVTH162244 devices are 16-bit buffers/line drivers designed for low-voltage 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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 **TEXAS
INSTRUMENTS**

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SN54ALVTH162244, SN74ALVTH162244

2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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description (continued)

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

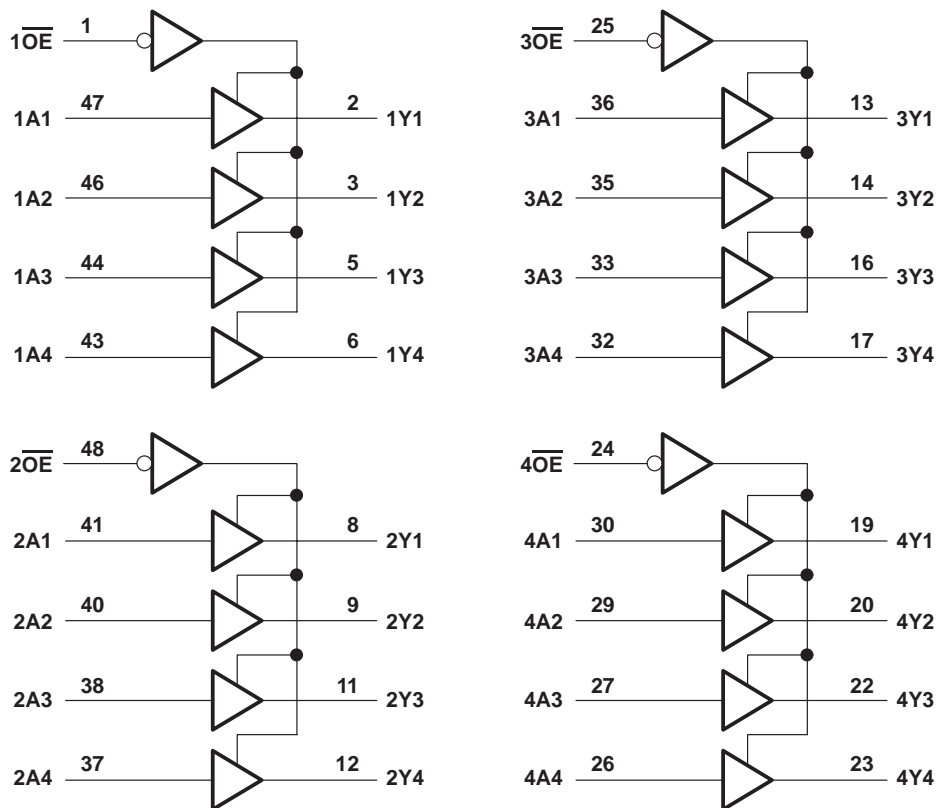
All outputs are designed to sink up to 12 mA and include equivalent 30- Ω resistors to reduce overshoot and undershoot.

The SN54ALVTH162244 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALVTH162244 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



SN54ALVTH162244, SN74ALVTH162244

2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54ALVTH162244		SN74ALVTH162244		UNIT
			MIN	TYP†	MAX	MIN	
V_{IK}	$V_{CC} = 2.3 \text{ V}$, $I_I = -18 \text{ mA}$		-1.2		-1.2		V
V_{OH}	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$, $I_{OH} = -100 \mu\text{A}$		$V_{CC}-0.2$		$V_{CC}-0.2$		V
	$V_{CC} = 2.3 \text{ V}$	$I_{OH} = -6 \text{ mA}$	1.7		1.7		
V_{OL}	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$, $I_{OL} = 100 \mu\text{A}$		0.2		0.2		V
	$V_{CC} = 2.3 \text{ V}$	$I_{OL} = 8 \text{ mA}$	0.7		0.7		
		$I_{OL} = 12 \text{ mA}$	0.7		0.7		
I_I	Control inputs	$V_{CC} = 2.7 \text{ V}$, $V_I = V_{CC} \text{ or GND}$	± 1		± 1		μA
		$V_{CC} = 0 \text{ or } 2.7 \text{ V}$, $V_I = 5.5 \text{ V}$	10		10		
	Data inputs	$V_{CC} = 2.7 \text{ V}$, $V_I = 5.5 \text{ V}$	10		10		
		$V_{CC} = 2.7 \text{ V}$, $V_I = V_{CC}$	1		1		
		$V_{CC} = 2.7 \text{ V}$, $V_I = 0$	-5		-5		
I_{off}	$V_{CC} = 0$, $V_I \text{ or } V_O = 0 \text{ to } 4.5 \text{ V}$				± 100		μA
I_{BHL}^\ddagger	$V_{CC} = 2.3 \text{ V}$, $V_I = 0.7 \text{ V}$		115		115		μA
I_{BHH}^\S	$V_{CC} = 2.3 \text{ V}$, $V_I = 1.7 \text{ V}$		-10		-10		μA
I_{BHLO}^\P	$V_{CC} = 2.7 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$		300		300		μA
$I_{BHHO}^\#$	$V_{CC} = 2.7 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$		-300		-300		μA
I_{EX}^\parallel	$V_{CC} = 2.3 \text{ V}$, $V_O = 5.5 \text{ V}$		125		125		μA
$I_{OZ(PU/PD)}^\star$	$V_{CC} \leq 1.2 \text{ V}$, $V_O = 0.5 \text{ V to } V_{CC}$, $V_I = \text{GND or } V_{CC}$, $\overline{OE} = \text{don't care}$		± 100		± 100		μA
I_{OZH}	$V_{CC} = 2.7 \text{ V}$	$V_O = 2.3 \text{ V}$, $V_I = 0.7 \text{ V or } 1.7 \text{ V}$	5		5		μA
I_{OZL}	$V_{CC} = 2.7 \text{ V}$	$V_O = 0.5 \text{ V}$, $V_I = 0.7 \text{ V or } 1.7 \text{ V}$	-5		-5		μA
I_{CC}	$V_{CC} = 2.7 \text{ V}$, $I_O = 0$, $V_I = V_{CC} \text{ or GND}$	Outputs high	0.04	0.1	0.04	0.1	mA
		Outputs low	2.3	4.5	2.3	4.5	
		Outputs disabled	0.04	0.1	0.04	0.1	
C_i	$V_{CC} = 2.5 \text{ V}$, $V_I = 2.5 \text{ V or } 0$		3		3		pF
C_o	$V_{CC} = 2.5 \text{ V}$, $V_O = 2.5 \text{ V or } 0$		6		6		pF

† All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The bus-hold circuit can sink at least the minimum low sustaining current at $V_{IL} \text{ max}$. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to $V_{IL} \text{ max}$.

§ The bus-hold circuit can source at least the minimum high sustaining current at $V_{IH} \text{ min}$. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to $V_{IH} \text{ min}$.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| Current into an output in the high state when $V_O > V_{CC}$

☆ High-impedance state during power up or power down

SN54ALVTH162244, SN74ALVTH162244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54ALVTH162244		SN74ALVTH162244		UNIT		
			MIN	TYP†	MAX	MIN		TYP†	MAX
V_{IK}		$V_{CC} = 3 \text{ V}$, $I_I = -18 \text{ mA}$			-1.2		-1.2	V	
V_{OH}		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, $I_{OH} = -100 \mu\text{A}$	$V_{CC}-0.2$			$V_{CC}-0.2$		V	
		$V_{CC} = 3 \text{ V}$, $I_{OH} = -8 \text{ mA}$	2						
V_{OL}		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, $I_{OL} = 100 \mu\text{A}$			0.2		0.2	V	
		$V_{CC} = 3 \text{ V}$, $I_{OL} = 8 \text{ mA}$			0.8				
		$V_{CC} = 3 \text{ V}$, $I_{OL} = 12 \text{ mA}$					0.8		
I_I	Control inputs	$V_{CC} = 3.6 \text{ V}$, $V_I = V_{CC} \text{ or GND}$			± 1		± 1	μA	
		$V_{CC} = 0 \text{ or } 3.6 \text{ V}$, $V_I = 5.5 \text{ V}$			10		10		
	Data inputs	$V_{CC} = 3.6 \text{ V}$, $V_I = 5.5 \text{ V}$			10		10		
		$V_{CC} = 3.6 \text{ V}$, $V_I = V_{CC}$			1		1		
		$V_{CC} = 3.6 \text{ V}$, $V_I = 0$			-5		-5		
I_{off}		$V_{CC} = 0$, $V_I \text{ or } V_O = 0 \text{ to } 4.5 \text{ V}$					± 100	μA	
I_{BHL}^\ddagger		$V_{CC} = 3 \text{ V}$, $V_I = 0.8 \text{ V}$	75			75		μA	
I_{BHH}^\S		$V_{CC} = 3 \text{ V}$, $V_I = 2 \text{ V}$	-75			-75		μA	
I_{BHLO}^\P		$V_{CC} = 3.6 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$	500			500		μA	
$I_{BHHO}^\#$		$V_{CC} = 3.6 \text{ V}$, $V_I = 0 \text{ to } V_{CC}$	-500			-500		μA	
$I_{EX}^{\ \}$		$V_{CC} = 3 \text{ V}$, $V_O = 5.5 \text{ V}$			125		125	μA	
$I_{OZ(PU/PD)}^\star$		$V_{CC} \leq 1.2 \text{ V}$, $V_O = 0.5 \text{ V to } V_{CC}$, $V_I = \text{GND or } V_{CC}$, $\overline{OE} = \text{don't care}$			± 100		± 100	μA	
I_{OZH}		$V_{CC} = 3.6 \text{ V}$, $V_O = 3 \text{ V}$, $V_I = 0.8 \text{ V or } 2 \text{ V}$			5		5	μA	
I_{OZL}		$V_{CC} = 3.6 \text{ V}$, $V_O = 0.5 \text{ V}$, $V_I = 0.8 \text{ V or } 2 \text{ V}$			-5		-5	μA	
I_{CC}		$V_{CC} = 3.6 \text{ V}$, $I_O = 0$, $V_I = V_{CC} \text{ or GND}$	Outputs high		0.07	0.1	0.07	0.1	mA
			Outputs low		3.2	5	3.2	5	
			Outputs disabled		0.07	0.1	0.07	0.1	
ΔI_{CC}^\square		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at $V_{CC} \text{ or GND}$			0.4		0.4	mA	
C_i		$V_{CC} = 3.3 \text{ V}$, $V_I = 3.3 \text{ V or } 0$			3		3	pF	
C_o		$V_{CC} = 3.3 \text{ V}$, $V_O = 3.3 \text{ V or } 0$			6		6	pF	

† All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

§ The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

¶ An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least I_{BHHO} to switch this node from high to low.

|| Current into an output in the high state when $V_O > V_{CC}$

☆ High-impedance state during power up or power down

□ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ALVTH162244, SN74ALVTH162244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH162244		SN74ALVTH162244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	4.3	1	4.2	ns
t_{PHL}			1.4	3.8	1.5	3.7	
t_{PZH}	\overline{OE}	Y	1.3	6.9	1.4	6.8	ns
t_{PZL}			1.3	5.2	1.4	5.1	
t_{PHZ}	\overline{OE}	Y	1	4.7	1	4.6	ns
t_{PLZ}			1	3.6	1	3.5	

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ALVTH162244		SN74ALVTH162244		UNIT
			MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1	3.4	1	3.3	ns
t_{PHL}			1	3.4	1	3.3	
t_{PZH}	\overline{OE}	Y	1.4	5	1.5	4.9	ns
t_{PZL}			1.3	3.4	1.4	3.3	
t_{PHZ}	\overline{OE}	Y	1.4	5	1.5	4.9	ns
t_{PLZ}			1.4	4.4	1.5	4.3	

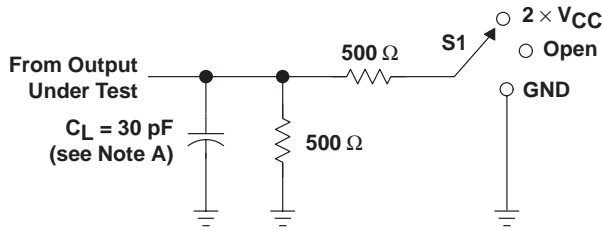
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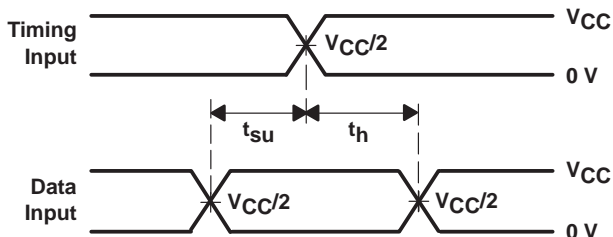
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$

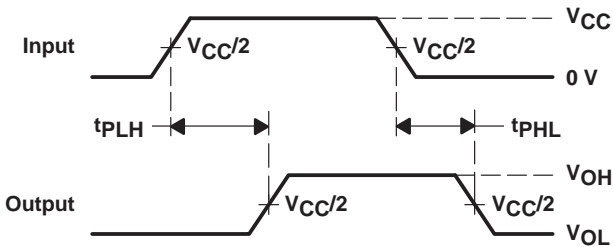


LOAD CIRCUIT

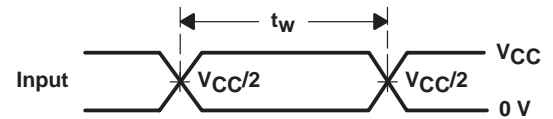
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 \times V_{CC}
t_{PHZ}/t_{PZH}	GND



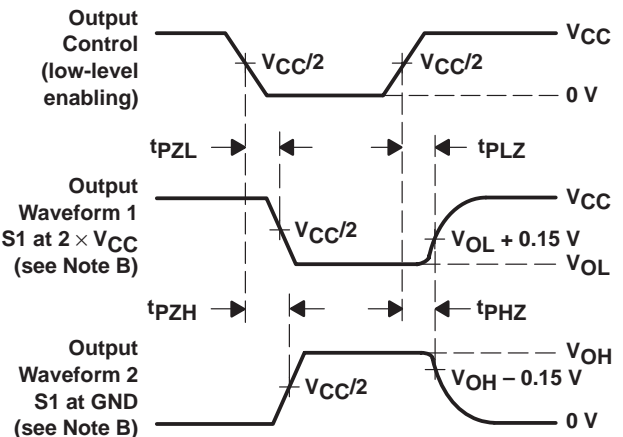
VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
 PULSE DURATION



VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50\ \Omega$, $t_r \leq 2\text{ ns}$, $t_f \leq 2\text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

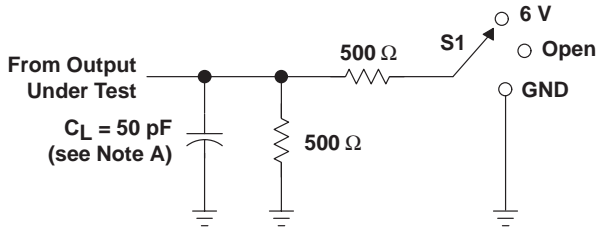
Figure 1. Load Circuit and Voltage Waveforms

SN54ALVTH162244, SN74ALVTH162244
2.5-V/3.3-V 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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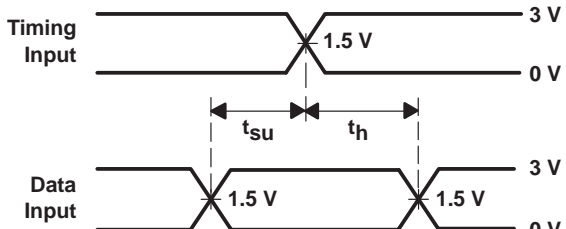
PARAMETER MEASUREMENT INFORMATION

$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$

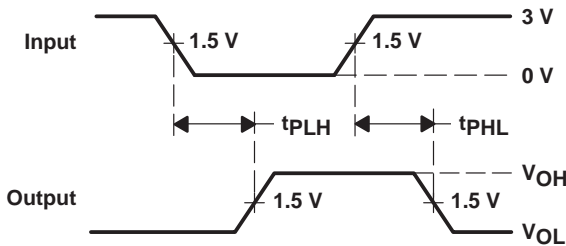


LOAD CIRCUIT

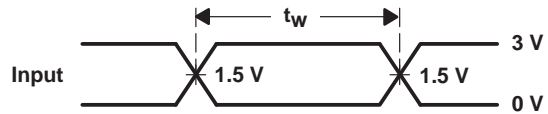
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



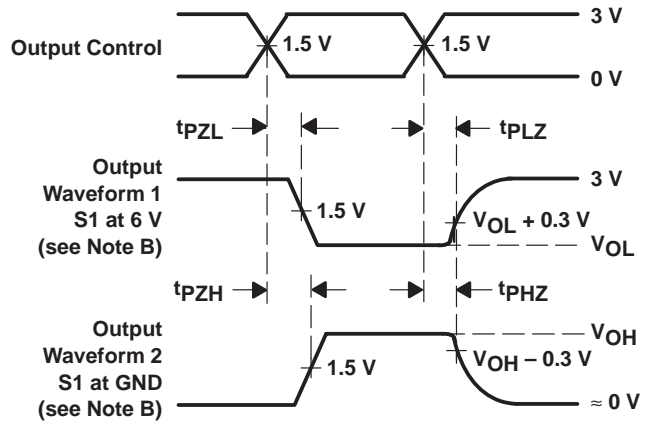
**VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
PULSE DURATION**



**VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVTH162244DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244GRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244LRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244VRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH162244VRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH162244VR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

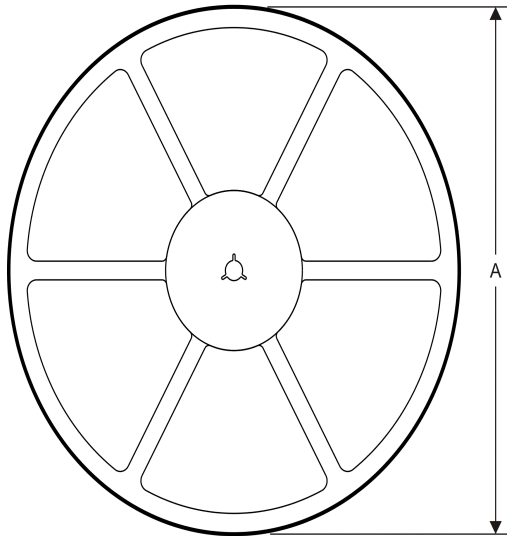
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVTH162244GR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74ALVTH162244LR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ALVTH162244VR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVTH162244GR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ALVTH162244LR	SSOP	DL	48	1000	367.0	367.0	55.0
SN74ALVTH162244VR	TVSOP	DGV	48	2000	367.0	367.0	38.0

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

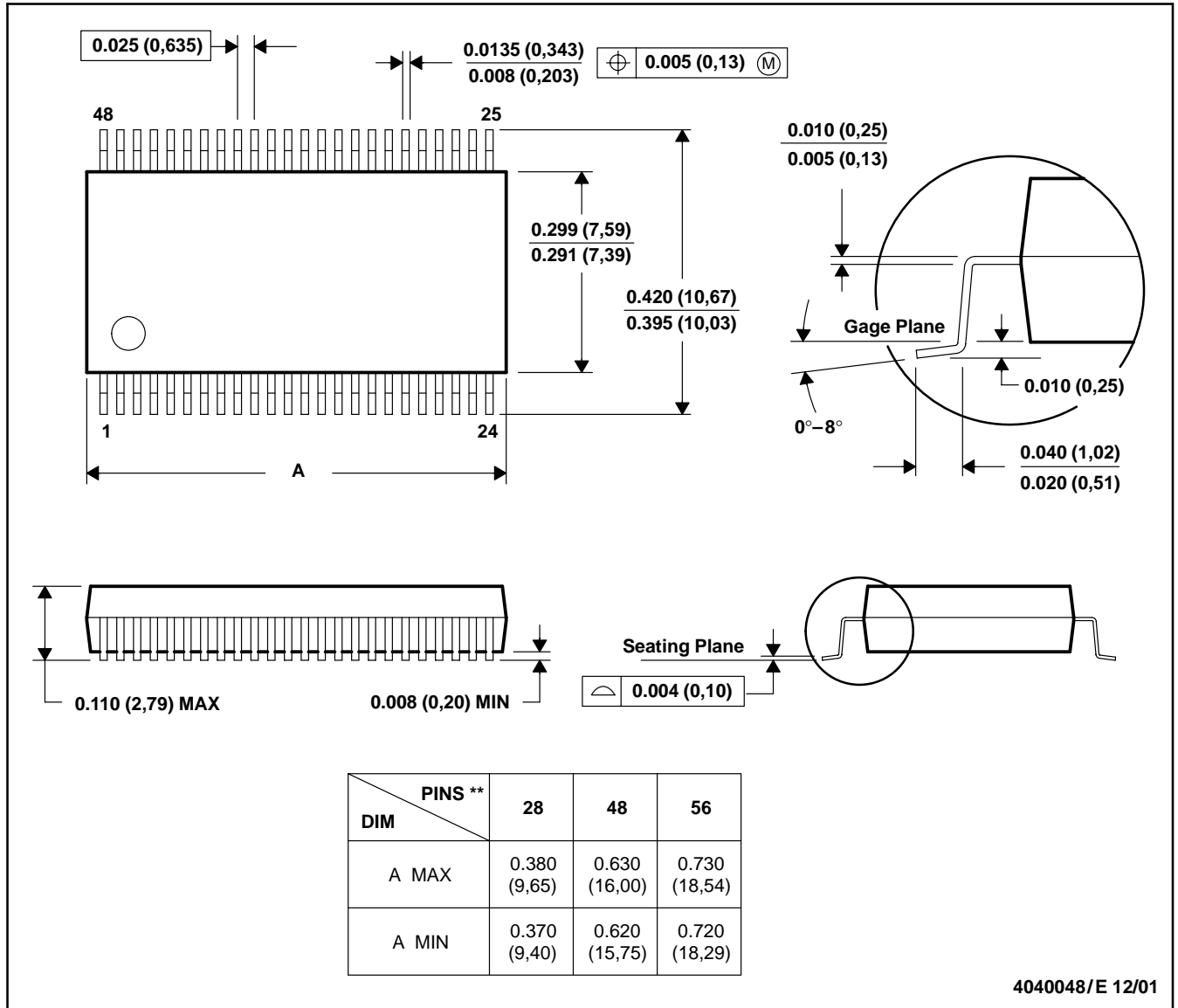


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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